

AMENDMENT TO CLAIMS

Please amend claim 1.

Please cancel claim 4.

Please add new claims 7-10

1. (Currently Amended) A semiconductor device comprising:

a semiconductor element having a primary surface and a back surface, said semiconductor element having an element electrode on the primary surface; and

a circuit board having a primary surface and a back surface, ~~said circuit board having~~ a board electrode on at least the back surface, ~~said circuit board having~~ and a predetermined opening hole formed therein;

wherein the primary surface of said semiconductor element is bonded to the primary surface of said circuit board by means of an adhesive layer which is greater in size than the primary surface of said semiconductor element,

said adhesive layer extends outside an outer edge of the primary surface of said semiconductor element without reaching an outer edge of the primary surface of said circuit board, said adhesive layer extending outward relative to and completely all the way around the primary surface of said semiconductor element,

said element electrode of said semiconductor element is connected to said board electrode provided on the back surface of said circuit board via said opening hole, and

said semiconductor element and said circuit board directly contact each other via the adhesive layer in order to relieve tension between said semiconductor element and said circuit board by the adhesive layer.

2. (Original) The semiconductor device as according to claim 1, wherein the surrounding regions of the side surfaces of said semiconductor element on said circuit board are sealed with resin so as to assume a flange structure.

3. (Original) The semiconductor device as according to claim 1, wherein the surrounding regions of the side surfaces and back surface of said semiconductor element are sealed with resin.

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Claims 4-6 (Cancelled)

7. (New) A method of reducing tension between a semiconductor element and a circuit board provided in a semiconductor device, comprising the steps of:

preparing said semiconductor element and circuit board; and

bonding said semiconductor element to said circuit board through an adhesive layer which extends outside an edge of said semiconductor element without reaching an edge of said circuit board, said adhesive layer extending outward relative to and completely all the way around the primary surface of said semiconductor element.

8. (New) The method according to claim 7, further comprising the step of sealing said semiconductor element and circuit board with resin.

9. (New) The method according to claim 8, wherein said sealing step puts the resin only on the surface of the circuit board on which the semiconductor element is

bonded through the adhesive layer so that the semiconductor element are surrounded by the resin to have a flange structure.

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10. (New) The method according to claim 8, wherein said sealing step puts the resin only on the surface of the circuit board on which the semiconductor element is bonded through the adhesive layer so that the semiconductor element are covered by the resin.
